

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	225	sato-shuzo.in. yasuda-zenya.in. komai-naoki.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:46
S2	3534	205/640-686.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:48
S3	10	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 10:55
S4	307866	sony.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:54
S5	11	S4 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:54
S6	8	S5 not S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:56
S7	308349	centripetal centrifugal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:57
S8	79	S7 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/05 17:58

S9	452	(drop dropp\$3 place plac\$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 flow flow\$3) with (electrolyte slurry "electropolishing fluid") with (center middle inner) with (workpiece work substrate microelectronic wafer)	US-PGPUB; USPAT; USCOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 11:05
S10	452	(drop dropp\$3 place plac\$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 (flow not (flow adj rate)) flow\$3) with (electrolyte slurry "electropolishing fluid") with (center middle inner) with (workpiece work substrate microelectronic wafer)	US-PGPUB; USPAT; USCOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 11:01
S11	149	((drop dropp\$3 place plac\$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 flow flow\$3) with (electrolyte slurry "electropolishing fluid") with (center middle inner) with (pad)) and (workpiece work substrate microelectronic wafer) and (CMP (chemical adj mechanical polishing) electropolishing electropolish)	US-PGPUB; USPAT; USCOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 11:06
S12	66	((drop dropp\$3 place plac\$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 flow flow\$3) with (electrolyte slurry "electropolishing fluid") with ((center middle inner) near2 (pad))) and (workpiece work substrate microelectronic wafer) and (CMP (chemical adj mechanical polishing) electropolishing electropolish)	US-PGPUB; USPAT; USCOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:01

S13	18	(US-20040149592-\$ or US-20020088709-\$ or US-20030141201-\$ or US-20030121797-\$ or US-20050124267-\$ or US-20050113006-\$ or US-20040242126-\$ or US-20050037936-\$ or US-20040116313-\$ or US-20040087257-\$).did. or (US-6582578-\$ or US-6551488-\$ or US-6899609-\$ or US-6461230-\$ or US-6409577-\$ or US-6238270-\$ or US-5879226-\$ or US-5866480-\$).did.	US-PGPUB; USPAT	OR	ON	2006/09/06 11:49
S14	0	S13 and ((recycle cup collect) with (electrolyte slurry "polishing fluid"))	US-PGPUB; USPAT	OR	ON	2006/09/06 11:50
S15	18	(US-20040149592-\$ or US-20020088709-\$ or US-20030141201-\$ or US-20030121797-\$ or US-20050124267-\$ or US-20050113006-\$ or US-20040242126-\$ or US-20050037936-\$ or US-20040116313-\$ or US-20040087257-\$).did. or (US-6582578-\$ or US-6551488-\$ or US-6899609-\$ or US-6461230-\$ or US-6409577-\$ or US-6238270-\$ or US-5879226-\$ or US-5866480-\$).did.	US-PGPUB; USPAT	OR	ON	2006/09/06 11:57
S16	6	S15 and (cathode anode electrode)	US-PGPUB; USPAT; USCOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 11:57
S17	4	((drop dropp\$3 place plac \$3 deliver deliver\$3 dispose disposed apply applying applicat\$3 discharg\$3 flow flow\$3) with (electrolyte slurry "electropolishing fluid") with ((center middle inner) near2 (pad))) and (workpiece work substrate microelectronic wafer) and (EMP (electomechanical adj polishing) electropolishing electropolish)	US-PGPUB; USPAT; USCOR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:05

S18	3534	205/640-686.cds.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:05
S19	522	S18 and (ECMP (electrochemical adj mechanical adj polishing) electropolishing electropolish)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:06
S20	138	S18 and (ECMP (electrochemical adj mechanical adj polishing) electropolishing electropolish) and pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:08
S21	8	S18 and (ECMP (electrochemical adj mechanical adj polishing) electropolishing electropolish) and (pad near2 (center middle))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/06 12:07
S22	213	((ECMP CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3)) (electrochemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same (((abrasive adj grains) alumina)) with (control specifying specif\$3 controll \$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 16:57
S23	0	(ECMP (electrochemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same (((abrasive adj grains) alumina)) with (control specifying specif\$3 controll \$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 16:56
S24	213	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same (((abrasive adj grains) alumina)) with (control specifying specif\$3 controll \$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 16:58

S25	213	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same (((abrasive adj grains) alumina) with (control specifying specif\$3 controll \$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:00
S26	159	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) same ((alumina) with (control specifying specif\$3 controll \$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 16:59
S27	23	(US-20040149592-\$ or US-20030141201-\$ or US-20030121797-\$ or US-20020088709-\$ or US-20030116446-\$ or US-20050124267-\$ or US-20050113006-\$ or US-20050037936-\$ or US-20040242126-\$ or US-20040116313-\$ or US-20040087257-\$ or US-20050145507-\$).did. or (US-6551488-\$ or US-6582578-\$ or US-5866480-\$ or US-6899609-\$ or US-6461230-\$ or US-6409577-\$ or US-6238270-\$ or US-5879226-\$ or US-6464855-\$ or US-5911619-\$ or US-5807165-\$).did.	US-PGPUB; USPAT	OR	ON	2006/11/29 17:00
S28	1	S27 and S25	US-PGPUB; USPAT	OR	ON	2006/11/29 17:00
S29	144	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) with (((abrasive adj grains) alumina) with (control specifying specif\$3 controll \$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:08

S30	1	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and (nozzle same (slurry solution electrolyte) with (((abrasive adj grains) alumina) with (control specifying specif\$3 controll \$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:03
S31	10	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) with (((abrasive adj grains) alumina) with (control specifying specif\$3 controll \$3))) and (nozzle with (slurry alumina (abrasive adj grain)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:04
S32	7	(CMP (chemical adj mechanical adj (polish polish\$3 planariz\$3 etch etch\$3))) and ((slurry solution electrolyte) with (((abrasive adj grains) alumina) with (control specifying specif\$3 controll \$3) with amount))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:21
S33	7	S32 not S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 17:09
S34	13	("2003/0116446").URPN.	USPAT	OR	ON	2006/11/29 17:20
S35	146	("20010016469" "20010024878" "20010036746" "20010042690" "20020008036" "20020016064" "20020016073" "20020016272" "20020040100" "20020070126" "20020072309" "20020074230" "20020088709" "20020096659" "20020108861" "20020130049" "20020139055" "20020160698"	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/29 17:21

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S36	6	S35 and (substrate adj support)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 18:01
S37	2	"5807165".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/29 18:01
S38	4	("6206760" "6402598" "6405399" "6595831"). PN.	US-PGPUB; USPAT	OR	ON	2006/11/30 13:47
S39	2	"6176992".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/05/17 15:47
S42	332	(ECMP ((electrochemical electrochemically electrolytic electrolytically) adj (mechanical mechanically) adj (polish polish\$3 planariz \$3 etch etch\$3 planarization process process\$3))) and (@pd< "20030124" @ad< "20030124")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/05 11:33
S43	2	"6176992".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/05 12:33

S44	337	(ECMP ((electrochemical electrochemically electrolytic electrolytically electro-chemical) adj (mechanical mechanically) adj (polish polish\$3 planariz\$3 etch etch\$3 planarization process process\$3))) and (@pd<"20030124" @ad<"20030124"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/05 12:34
S45	22	09/595727	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/05 12:37
S46	28	smith-nicholas-a.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/05 15:24

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